



Product Change Notice

(PCN No.: 02/03)

Customer: *all*

IXYS product type: *Packages: see page 2*

Description of change: *introduction of new lead-free paste soldering process in module assembly*

Reason for change: *(1) lead-free chip soldering
(2) improved thermal performance by better die attach quality
(3) automation of soldering process*

Identification: *Suffix letter change to "P" in Datecode*

Schedule of change: *Starting June 2003 for products VUB72, VUO34 and VUO52
Plan for completion: end of December 2003*

Influence on reliability: *improved reliability due to (2) and (3) (see reasons for change)*

Internal reference: *TÄ060/03*

In case of any question, please contact

Initiator	Title/Function	Date	e-mail
<i>Ostmann</i>	<i>MP1 / Product marketing</i>	<i>19.05.2003</i>	<i>h.ostmann@ixys.de</i>

IXYS Semiconductor GmbH
 Edisonstr. 15
 D-68623 Lampertheim
 Phone: +49-6206-503-564
 Fax: +49-6206-503-627

Customer response:

(please fill in and return by e-mail, fax or mail within 4 weeks)

for further questions / information Company: _____

please comment Name & Position: _____

Phone / Fax No.: _____

Note: **Written** response or **written** acknowledgement with statement of approval criteria, must be received within thirty (30) days of the date of this PCN or IXYS will consider this change approved.

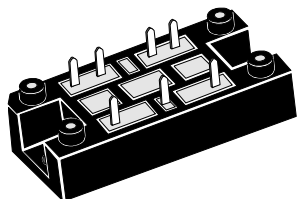
Comments: _____

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Picture:

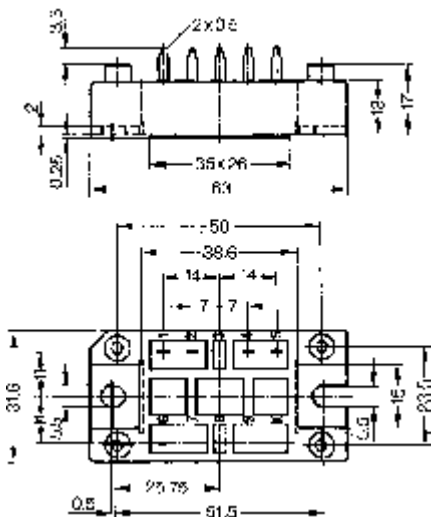
a)



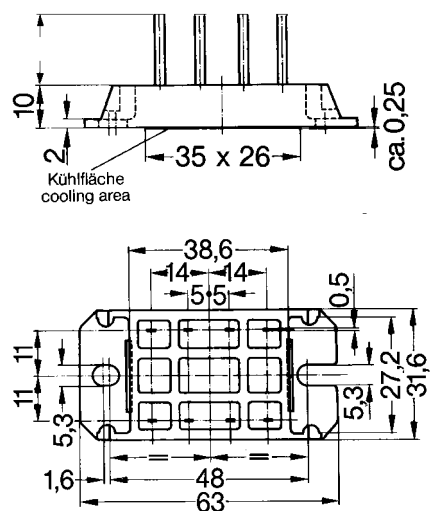
b)

Dimensions (in mm):

a)



b)

Products:

a) VUO16, VUO22, VUO34
 VUO52, VUO80
 VHFD16, VHFD29, VHFD37
 VW2x60, VW45, VW30
 VUE50, VUE30
 VBE20
 VUM25
 VUI30
 VUB72

b) VUC25, VUC36
 VVZ12, VVZ24, VVZ40
 VVY40
 VEE60
 VUM24, VUM33